

Title (en)

SYSTEMS AND METHODS FOR TREATING A SUBSTRATE

Title (de)

SYSTEME UND VERFAHREN ZUR BEHANDLUNG EINES SUBSTRATS

Title (fr)

SYSTÈMES ET PROCÉDÉS DE TRAITEMENT D'UN SUBSTRAT

Publication

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Application

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Abstract (en)

[origin: WO2022197358A1] Disclosed herein is a composition comprising a first lanthanide series metal, wherein the composition has a pH of less than 2.0 and is substantially free of peroxide. Also disclosed herein is a composition comprising a first lanthanide series metal and at least one of a second lanthanide series metal, copper, an inorganic phosphate compound, an organophosphate compound, and an organophosphonate compound; wherein the composition is substantially free of peroxide. Also disclosed herein are systems and methods of treating a metal substrate. Also disclosed are substrates treated with the systems and methods.

IPC 8 full level

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